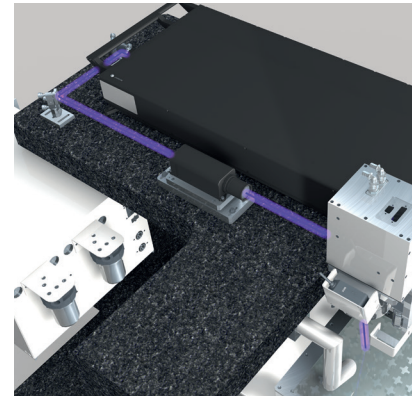
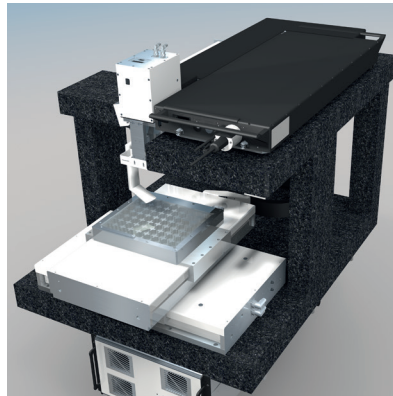
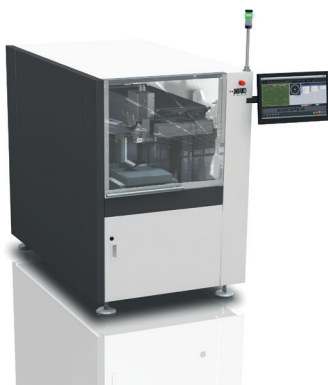


## DIVISIO 8000/8100



### Description

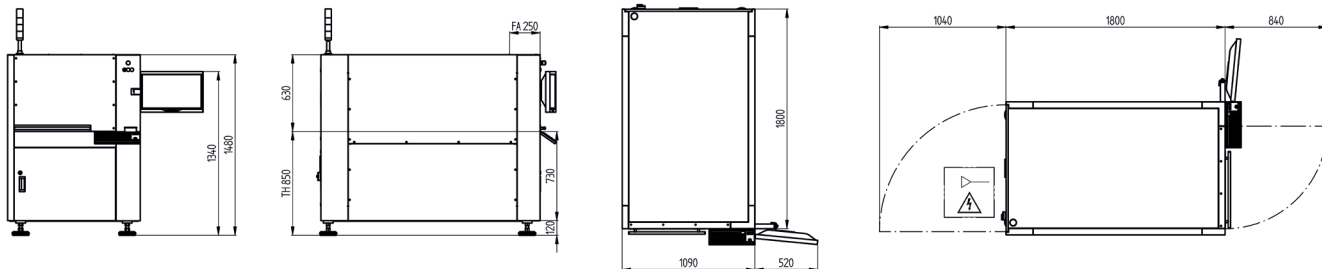
The DIVISIO 8000 Series is a machine platform for laser depaneling of rigid and flex PCBs. A hard stone base allows for maximum stability and precision. Different beam sources are available to adapt the laser cutting process to the substrate material. The system is available as a stand-alone manual loading system or fully automated in-line. For in-line operation various product specific carrier transport and fixture systems are available. Camera vision is used for machine calibration and offset correction by fiducials. The system uses a precise XY-stage and a fast galvo scanner for a step&scan process to optimize throughput and accuracy.

### Features

- \_ Dust free and stress free depaneling of flexible and rigid PCBs
- \_ High positioning accuracy
- \_ DIN language controlled (CNC) cutting recipes
- \_ Integrated camera vision system
- \_ State of the art beam sources and optics for improved cutting result

### Options

- \_ 7 W UV Laser for flex and thin FR4 material
- \_ 14 W UV Laser for higher throughput
- \_ 30 W Green Laser for cutting thick FR4
- \_ 40 W Green Laser for higher throughput
- \_ CO<sub>2</sub>-Laser for polyimide cutting and niche applications
- \_ Focus shift for thicker PCBs and to match carrier height
- \_ Laser power measurement
- \_ Laser power calibration
- \_ ASYCAM software for easy import of CAD (DXF) data
- \_ Exhaust and filter system
- \_ External water chiller
- \_ Database integration
- \_ Inline transport on carriers and carrier return systems



## DIVISIO 8000/8100

### DIVISIO 8000

### DIVISIO 8100

#### Machine Configuration

Transport height	950 mm ± 50 mm	
Operating side	Front of the machine	
Working Area	305 mm × 250 mm	460 mm × 305 mm
Scan field	50 mm × 50 mm up to 80 mm × 80 mm (depending of wavelength)	

#### Panel Dimensions

Panel length	20 to 305 mm	20 to 460 mm
Panel width	20 to 250 mm	20 to 305 mm
Panel thickness	recommended: 0.1 to 1.6 (2.0) mm	
Panel weight max.	4 kg	
PCB weight max.	1.5 kg	
Component clearance	+ 40 mm / 0 mm for manual loading, other options on request	

#### Installation Requirements

Power supply	3/N/ PE AC 400/230V 50 Hz (additional options on request)		
Power consumption	UV-Laser 5.6 kW avg., 7.2 kW peak GR-Laser 2.7 kW avg.		
CDA supply	6 bar		
CDA consumption	20 NI/min		
Water cooling	10l/min, 15°C,	1.2 kW 7W UV-Laser 2.0 kW 14W UV-Laser	3l/min, 20°C 500W 30W GR Laser 600W 40W GR Laser
Ambient Temperature	7.5 l/min., 18...20°C, 1.7 kW 100W CO2-Laser External AW-chiller comprised with GR-Laser option		
Humidity	22°C ± 1°C 50% ± 20% (non cond.)		

#### Machine Description

Length × width × height	1090 × 1800 × 1455 mm	1400 × 1800 × 1570 mm
Clearance at back side	1040 mm	670 mm
Laser type	UV 343 nm GR 532nm CO2 9300nm (others on request)	
Laser-class	1	
Positioning accuracy	± 15 µm @ 4 STD	
Repeatability accuracy	± 5 µm @ 4 STD	
Cutting accuracy	± 25 µm with Vision System @ 4 STD	
Fiducial camera	25 mm × 18 mm FoV	
Weight	approx. 1725 Kg	2200 Kg
Color	Basic Light/ RAL 7015/ RAL 4010	
Noise Level	< 75 dB(A)	

**ASYS  
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